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Application ID: 10667227



Title of Invention: SEMICONDUCTOR PACKAGE AND
METHOD OF MAKING
LEADFRAME HAVING LEAD
LOCKS TO SECURE LEADS TO
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

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Statement

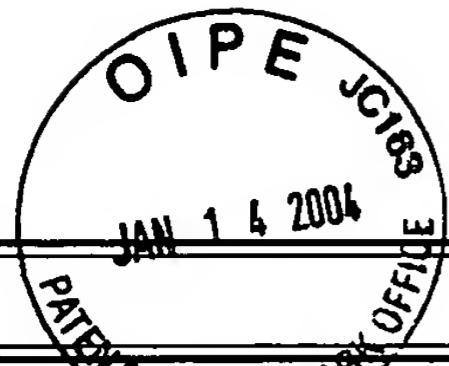
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Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

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Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT
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Application Number: 10/667227 
Date: 2003-09-18
First Named Applicant: Jae Hak Yee

Confirmation Number: 7012
Attorney Docket Number: AMKOR012G1

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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

Documents being submitted	Files
us-ids	ids5-usidst.xml
	us-ids.dtd
	us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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Application Number: 10/667227



Confirmation Number: 7012

First Named Applicant: Jae Yee

Attorney Docket Number: AMKOR012G1

Art Unit: 2812

Search string: (6194777 or 6198171 or 6197615 or 6201292
or 6201186 or 6204554 or 6208023 or 6208021
or 6208020 or 6211462 or 6218731 or 6222258
or 6225146 or 6229205 or 6229200 or 6239384
or 6239367 or 6242281 or 6256200 or 6258629
or 6282095 or 6281568 or 6281566 or 6285075
or 6291273 or 6291271 or 6294830 or 6294100
or 6297548 or 6295977 or 6303997 or 6303984
or 6307272 or 6309909 or 6316838 or 6316822
or 6323550 or 6326678 or 6326244 or 6326243
or 6335564 or 6337510 or 6339255 or 6348726
or 6355502 or 6369454 or 6369447 or 6373127
or 6380048 or 6384472).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	6198171	2001-03-06	HUANG ET AL			
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Signature

Examiner Name	Date